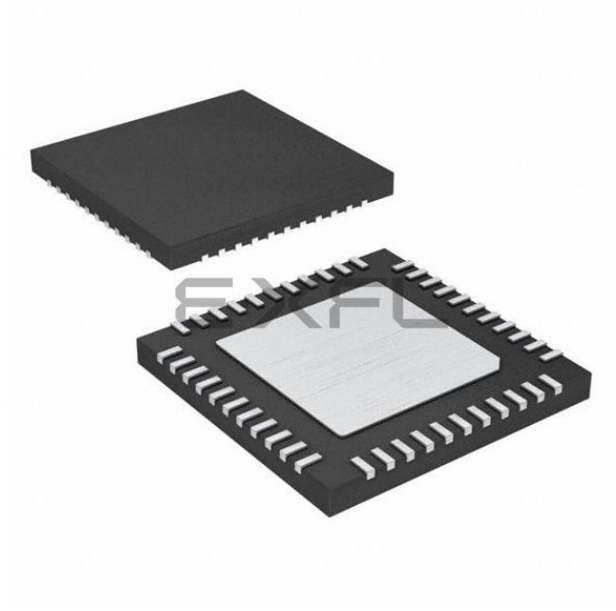

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8/16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFQFN Exposed Pad
Supplier Device Package	44-VQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atxmega16d4-mhk

24. CRC – Cyclic Redundancy Check Generator

24.1 Features

- Cyclic redundancy check (CRC) generation and checking for
  - Communication data
  - Program or data in flash memory
  - Data in SRAM and I/O memory space
- Integrated with flash memory and CPU
  - Automatic CRC of the complete or a selectable range of the flash memory
  - CPU can load data to the CRC generator through the I/O interface
- CRC polynomial software selectable to
  - CRC-16 (CRC-CCITT)
  - CRC-32 (IEEE 802.3)
- Zero remainder detection

24.2 Overview

A cyclic redundancy check (CRC) is an error detection technique test algorithm used to find accidental errors in data, and it is commonly used to determine the correctness of a data transmission, and data present in the data and program memories. A CRC takes a data stream or a block of data as input and generates a 16- or 32-bit output that can be appended to the data and used as a checksum. When the same data are later received or read, the device or application repeats the calculation. If the new CRC result does not match the one calculated earlier, the block contains a data error. The application will then detect this and may take a corrective action, such as requesting the data to be sent again or simply not using the incorrect data.

Typically, an n-bit CRC applied to a data block of arbitrary length will detect any single error burst not longer than n bits (any single alteration that spans no more than n bits of the data), and will detect the fraction $1-2^{-n}$ of all longer error bursts. The CRC module in Atmel AVR XMEGA devices supports two commonly used CRC polynomials; CRC-16 (CRC-CCITT) and CRC-32 (IEEE 802.3).

- **CRC-16:**

  Polynomial: $x^{16}+x^{12}+x^5+1$

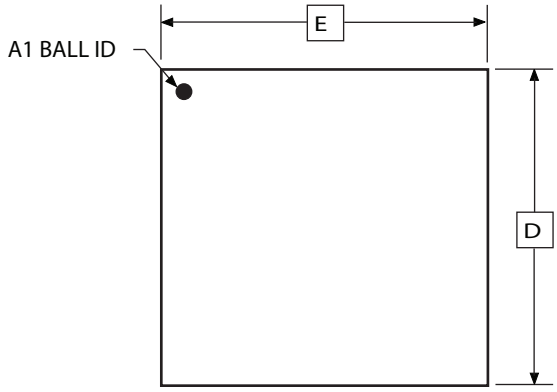
  Hex value: 0x1021

- **CRC-32:**

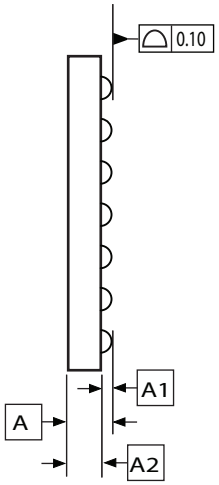
  Polynomial: $x^{32}+x^{26}+x^{23}+x^{22}+x^{16}+x^{12}+x^{11}+x^{10}+x^8+x^7+x^5+x^4+x^2+x+1$

  Hex value: 0x04C11DB7

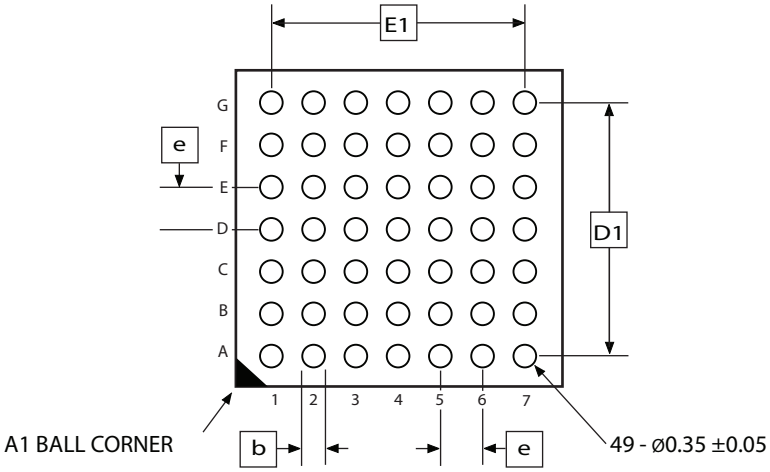
31.3 49C2



TOP VIEW



SIDE VIEW



BOTTOM VIEW

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.00	
A1	0.20	–	–	
A2	0.65	–	–	
D	4.90	5.00	5.10	
D1		3.90 BSC		
E4.90	5.00	5.10		
E1		3.90 BSC		
b	0.30	0.35	0.40	
e		0.65 BSC		

3/14/08

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE 49C2, 49-ball (7 x 7 array), 0.65mm pitch, 5.0 x 5.0 x 1.0mm, very thin, fine-pitch ball grid array package (VFBGA)	GPC CBD	DRAWING NO. 49C2	REV. A

Table 32-10. Accuracy Characteristics

Symbol	Parameter	Condition[2]		Min.	Typ.	Max.	Units
RES	Resolution	12-bit resolution	Differential	8	12	12	Bits
			Single ended signed	7	11	11	
			Single ended unsigned	8	12	12	
INL[1]	Integral non-linearity	Differential mode	16ksps, V_{REF} = 3V		0.5	1	lsb
			16ksps, all V_{REF}		0.8	2	
			200ksps, V_{REF} = 3V		0.6	1	
			200ksps, all V_{REF}		1	2	
		Single ended unsigned mode	16ksps, V_{REF} = 3.0V		0.5	1	
			16ksps, all V_{REF}		1.3	2	
DNL[1]	Differential non-linearity	Differential mode	16ksps, V_{REF} = 3V		0.3	1	
			16ksps, all V_{REF}		0.5	1	
			200ksps, V_{REF} = 3V		0.35	1	
			200ksps, all V_{REF}		0.5	1	
		Single ended unsigned mode	16ksps, V_{REF} = 3.0V		0.6	1	
			16ksps, all V_{REF}		0.6	1	
	Offset Error	Differential mode			8		mV
			Temperature drift		0.01		mV/K
			Operating voltage drift		0.25		mV/V
	Gain Error	Differential mode	External reference		-5		mV
			AV_{CC}/1.6		-5		
			AV_{CC}/2.0		-6		
			Bandgap		±10		
			Temperature drift		0.02		mV/K
			Operating voltage drift		2		mV/V
		Single ended unsigned mode	External reference		-8		mV
			AV_{CC}/1.6		-8		
			AV_{CC}/2.0		-8		
			Bandgap		±10		
			Temperature drift		0.03		mV/K
			Operating voltage drift		2		mV/V

Notes:
1. Maximum numbers are based on characterisation and not tested in production, and valid for 5% to 95% input voltage range.
2. Unless otherwise noted all linearity, offset and gain error numbers are valid under the condition that external VREF is used.

32.2.5 I/O Pin Characteristics

The I/O pins complies with the JEDEC LVTTL and LVCMOS specification and the high- and low level input and output voltage limits reflect or exceed this specification.

Table 32-35. I/O Pin Characteristics

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
I_{OH} (1)/ I_{OL} (2)	I/O pin source/sink current			-20		20	mA
V_{IH}	High level input voltage	V_{CC} = 2.4 - 3.6V		0.7*Vcc		V_{CC}+0.5	V
		V_{CC} = 1.6 - 2.4V		0.8*V_{CC}		V_{CC}+0.5	
V_{IL}	Low level input voltage	V_{CC} = 2.4- 3.6V		-0.5		0.3*V_{CC}	
		V_{CC} = 1.6 - 2.4V		-0.5		0.2*V_{CC}	
V_{OH}	High level output voltage	V_{CC} = 3.3V	I_{OH} = -4mA	2.6	2.9		
		V_{CC} = 3.0V	I_{OH} = -3mA	2.1	2.7		
		V_{CC} = 1.8V	I_{OH} = -1mA	1.4	1.6		
V_{OL}	Low level output voltage	V_{CC} = 3.3V	I_{OL} = 8mA		0.4	0.76	
		V_{CC} = 3.0V	I_{OL} = 5mA		0.3	0.64	
		V_{CC} = 1.8V	I_{OL} = 3mA		0.2	0.46	
I_{IN}	Input leakage current I/O pin	T = 25°C			<0.01	1	µA
R_P	Pull/buss keeper resistor				25		kΩ

Notes:
1. The sum of all I_{OH} for PORTA and PORTB must not exceed 100mA.
   The sum of all I_{OH} for PORTC, PORTD, PORTE must for each port not exceed 200mA.
   The sum of all I_{OH} for pins PF[0-5] on PORTF must not exceed 200mA.
   The sum of all I_{OL} for pins PF[6-7] on PORTF, PORTR and PDI must not exceed 100mA.
2. The sum of all I_{OL} for PORTA and PORTB must not exceed 100mA.
   The sum of all I_{OL} for PORTC, PORTD, PORTE must for each port not exceed 200mA.
   The sum of all I_{OL} for pins PF[0-5] on PORTF must not exceed 200mA.
   The sum of all I_{OL} for pins PF[6-7] on PORTF, PORTR and PDI must not exceed 100mA.

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
R_Q	Negative impedance	XOSCPWR=1, FRQRANGE=0, CL=20pF	9MHz crystal		390		Ω
			12MHz crystal		50		
			16MHz crystal		10		
		XOSCPWR=1, FRQRANGE=1, CL=20pF	9MHz crystal		1500		
			12MHz crystal		650		
			16MHz crystal		270		
		XOSCPWR=1, FRQRANGE=2, CL=20pF	12MHz crystal		1000		
			16MHz crystal		440		
		XOSCPWR=1, FRQRANGE=3, CL=20pF	12MHz crystal		1300		
			16MHz crystal		590		
	ESR	SF = safety factor				min(R_Q)/SF	kΩ
	Start-up time	XOSCPWR=0, FRQRANGE=0	0.4MHz resonator, CL=100pF		1.0		ms
		XOSCPWR=0, FRQRANGE=1	2MHz crystal, CL=20pF		2.6		
		XOSCPWR=0, FRQRANGE=2	8MHz crystal, CL=20pF		0.8		
		XOSCPWR=0, FRQRANGE=3	12MHz crystal, CL=20pF		1.0		
		XOSCPWR=1, FRQRANGE=3	16MHz crystal, CL=20pF		1.4		
C_{XTAL1}	Parasitic capacitance XTAL1 pin				5.9		pF
C_{XTAL2}	Parasitic capacitance XTAL2 pin				8.3		
C_{LOAD}	Parasitic capacitance load				3.5		

32.4 ATxmega128D4

32.4.1 Absolute Maximum Ratings

Stresses beyond those listed in Table 32-86 under may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 32-86. Absolute Maximum Ratings

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{CC}	Power supply voltage		-0.3		4	V
I_{VCC}	Current into a V_{CC} pin				200	mA
I_{GND}	Current out of a Gnd pin				200	
V_{PIN}	Pin voltage with respect to Gnd and V_{CC}		-0.5		V_{CC}+0.5	V
I_{PIN}	I/O pin sink/source current		-25		25	mA
T_A	Storage temperature		-65		150	°C
T_j	Junction temperature				150	

32.4.2 General Operating Ratings

The device must operate within the ratings listed in Table 32-87 in order for all other electrical characteristics and typical characteristics of the device to be valid.

Table 32-87. General Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{CC}	Power supply voltage		1.60		3.6	V
AV_{CC}	Analog supply voltage		1.60		3.6	
T_A	Temperature range		-40		85	°C
T_j	Junction temperature		-40		105	

Table 32-88. Operating Voltage and Frequency

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Clk_{CPU}	CPU clock frequency	V_{CC} = 1.6V	0		12	MHz
		V_{CC} = 1.8V	0		12	
		V_{CC} = 2.7V	0		32	
		V_{CC} = 3.6V	0		32	

32.4.3 Current Consumption

Table 32-89. Current Consumption for Active Mode and Sleep Modes

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
I_{CC}	Active power consumption[1]	32kHz, Ext. Clk	V_{CC} = 1.8V		55		µA
			V_{CC} = 3.0V		135		
		1MHz, Ext. Clk	V_{CC} = 1.8V		255		
			V_{CC} = 3.0V		535		
		2MHz, Ext. Clk	V_{CC} = 1.8V		460	600	
			V_{CC} = 3.0V		1.0	1.4	mA
		32MHz, Ext. Clk			9.5	12	
	Idle power consumption[1]	32kHz, Ext. Clk	V_{CC} = 1.8V		2.9		µA
			V_{CC} = 3.0V		3.9		
		1MHz, Ext. Clk	V_{CC} = 1.8V		62		
			V_{CC} = 3.0V		118		
		2MHz, Ext. Clk	V_{CC} = 1.8V		125	225	
			V_{CC} = 3.0V		240	350	
		32MHz, Ext. Clk			3.8	5.5	mA
	Power-down power consumption	T = 25°C	V_{CC} = 3.0V		0.1	1.0	µA
		T = 85°C			1.5	4.5	
		T = 105°C			0.1	8.6	
		WDT and sampled BOD enabled, T = 25°C	V_{CC} = 3.0V		1.4	3.0	
		WDT and sampled BOD enabled, T = 85°C			2.8	6.0	
		WDT and sampled BOD enabled, T = 105°C			1.4	8.8	
	Power-save power consumption[2]	RTC from ULP clock, WDT and sampled BOD enabled, T = 25°C	V_{CC} = 1.8V		1.2		
			V_{CC} = 3.0V		1.5		
		RTC from 1.024kHz low power 32.768kHz TOSC, T = 25°C	V_{CC} = 1.8V		0.6	2.0	
			V_{CC} = 3.0V		0.7	2.0	
		RTC from low power 32.768kHz TOSC, T = 25°C	V_{CC} = 1.8V		0.8	3.0	
			V_{CC} = 3.0V		1.0	3.0	
	Reset power consumption	Current through $\overline{\text{RESET}}$ pin substracted	V_{CC} = 3.0V		300		

Notes:
1. All Power Reduction Registers set.
2. Maximum limits are based on characterization, and not tested in production.

Figure 33-25. I/O Pin Output Voltage vs. Source Current

V_{CC} = 3.0V

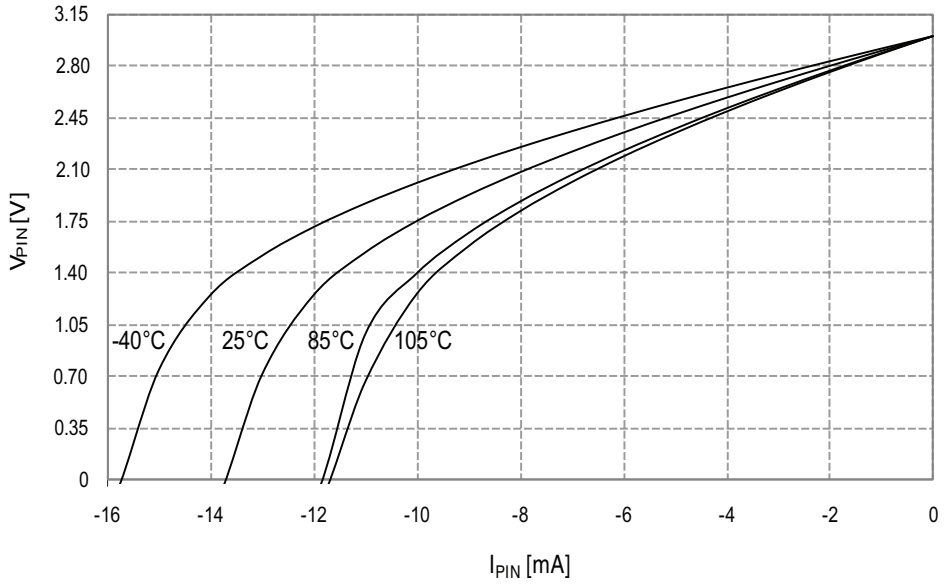


Figure 33-26. I/O Pin Output Voltage vs. Source Current

V_{CC} = 3.3V

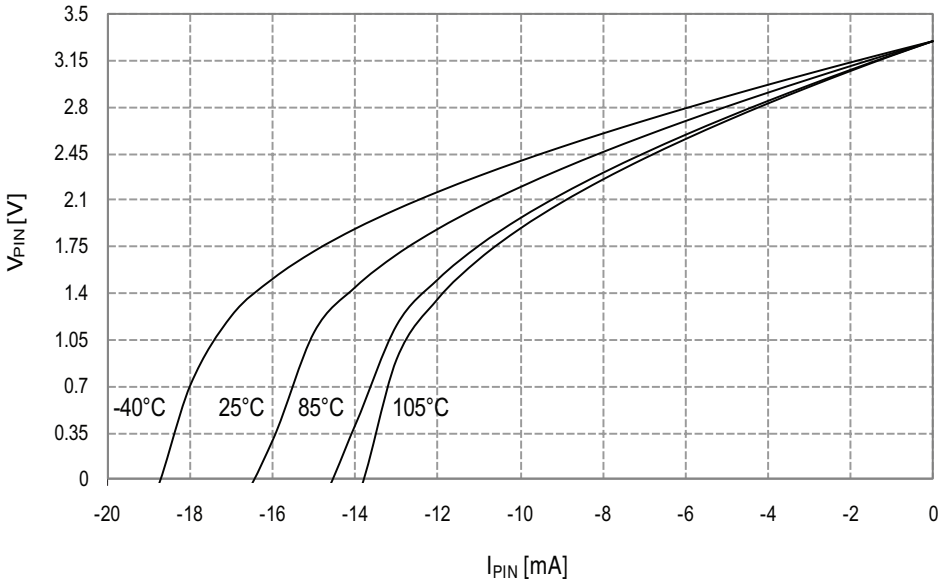


Figure 33-27. I/O Pin Output Voltage vs. Source Current

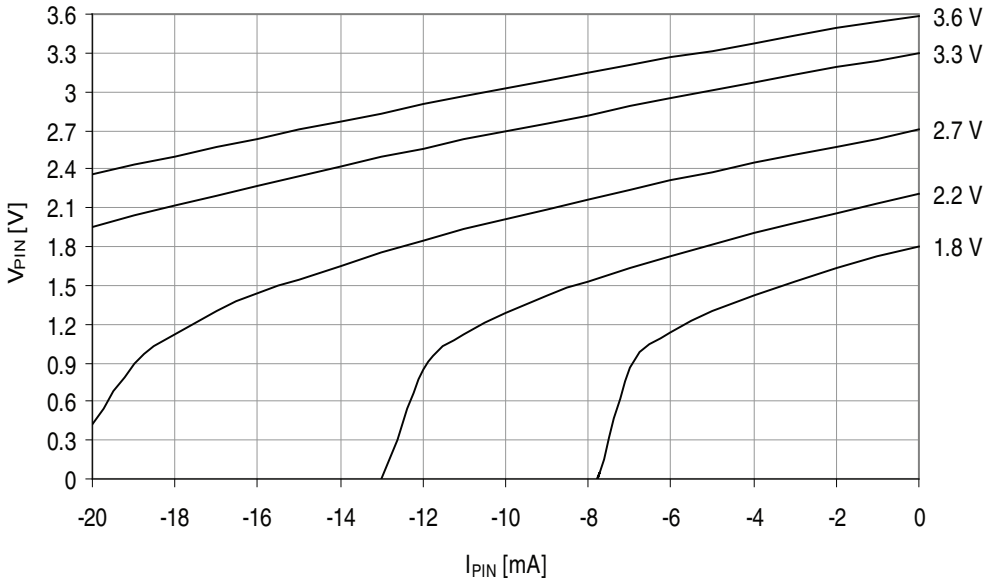


Figure 33-28. I/O Pin Output Voltage vs. Sink Current

V_{CC} = 1.8V

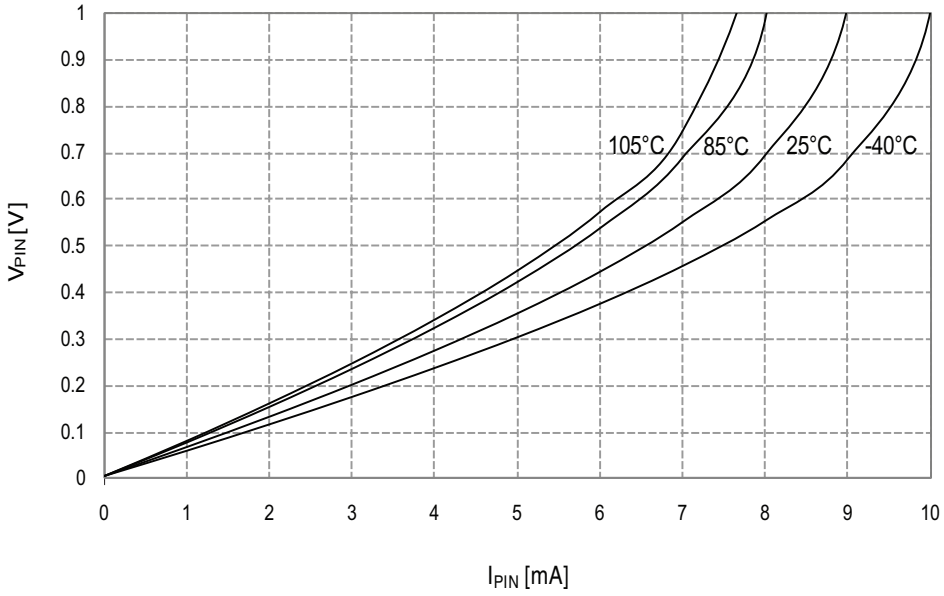


Figure 33-45. Gain Error vs. Temperature

V_{CC} = 3.0V, V_{REF} = external 2.0V

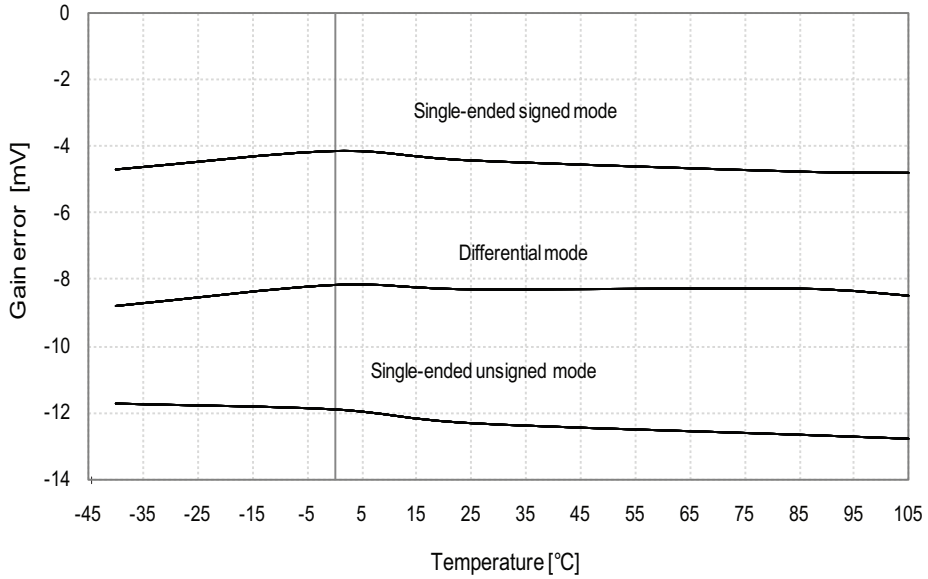
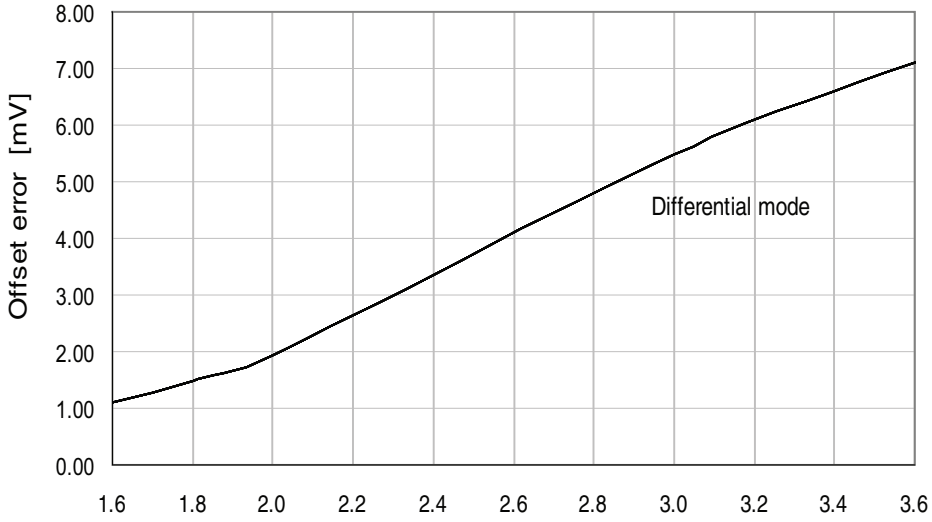


Figure 33-46. Offset Error vs. V_{CC}

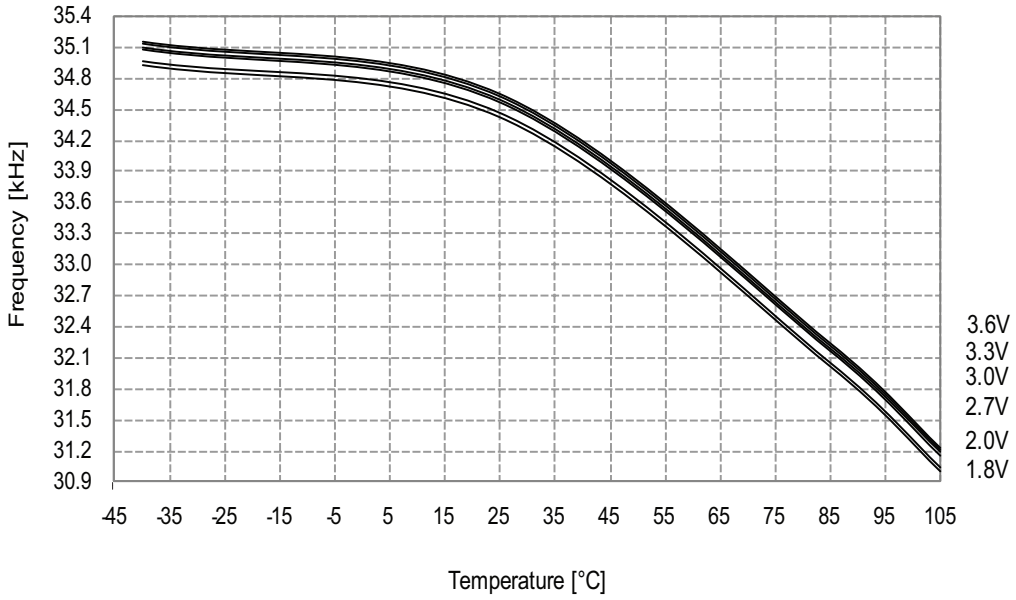
T = 25°C, V_{REF} = external 1.0V, ADC sample rate = 200ksps



33.1.9 Oscillator Characteristics

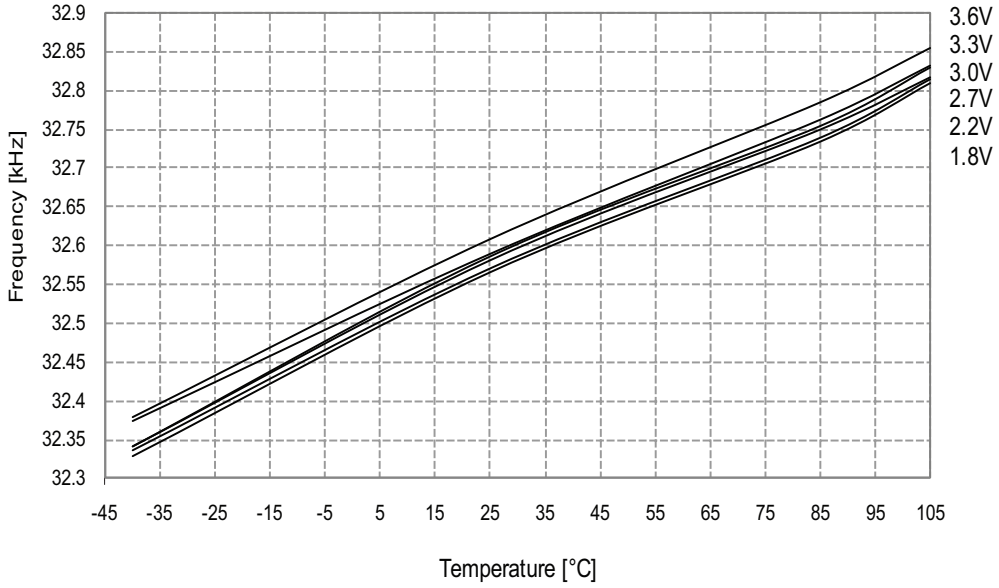
33.1.9.1 Ultra Low-Power Internal Oscillator

Figure 33-65. Ultra Low-Power Internal Oscillator Frequency vs. Temperature



33.1.9.2 32.768kHz Internal Oscillator

Figure 33-66. 32.768kHz Internal Oscillator Frequency vs. Temperature



33.1.10 Two-Wire Interface Characteristics

Figure 33-77. SDA Hold Time vs. Temperature

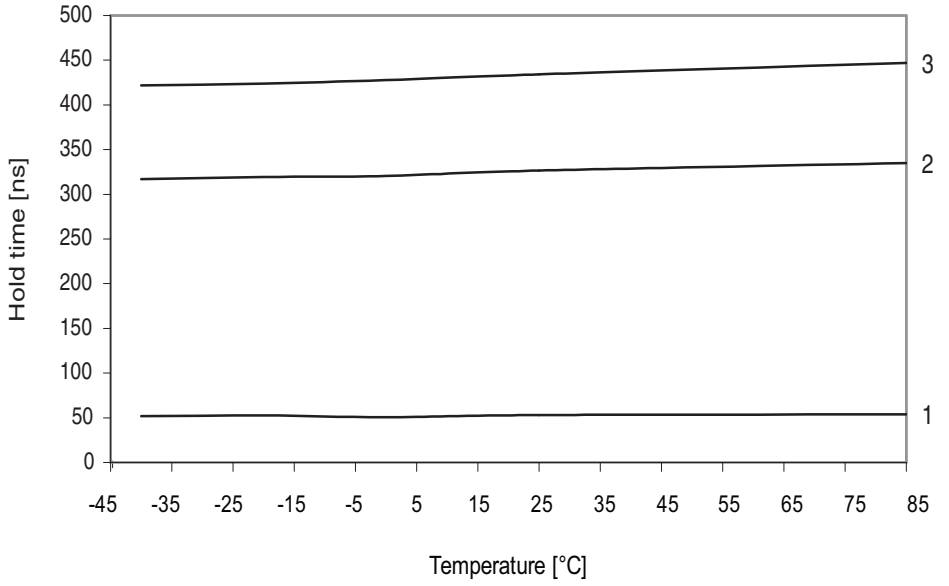


Figure 33-78. SDA Hold Time vs. Supply Voltage

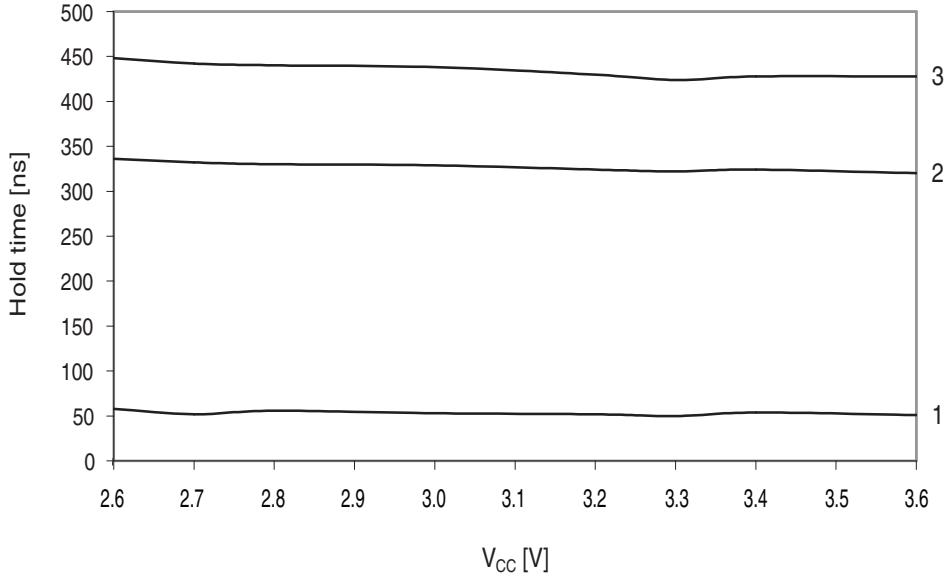
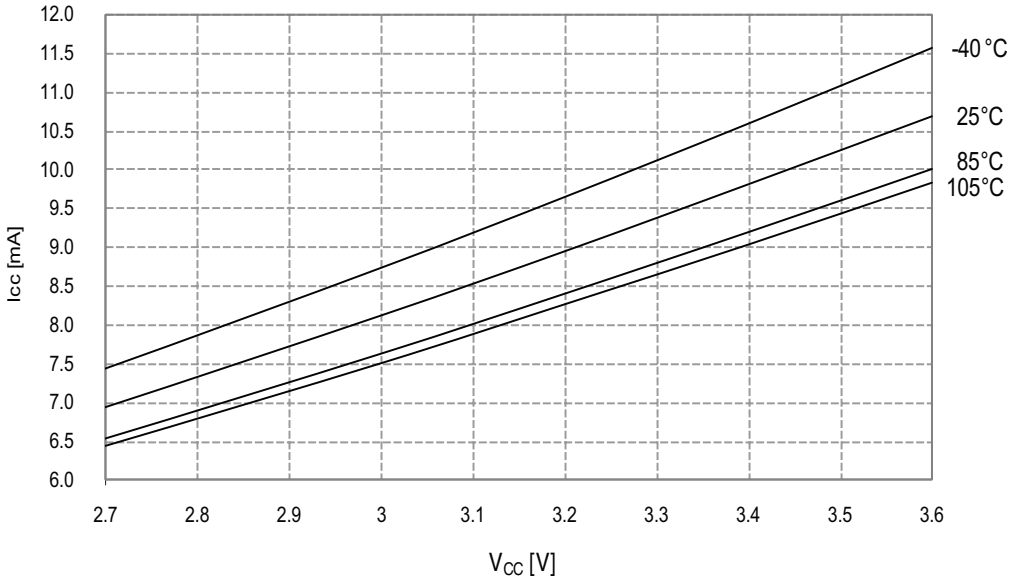


Figure 33-86. Active Mode Supply Current vs. V_{CC}

f_{SYS} = 32MHz internal oscillator



33.2.1.2 Idle Mode Supply Current

Figure 33-87. Idle Mode Supply Current vs. Frequency

f_{SYS} = 0 - 1MHz external clock, T = 25°C

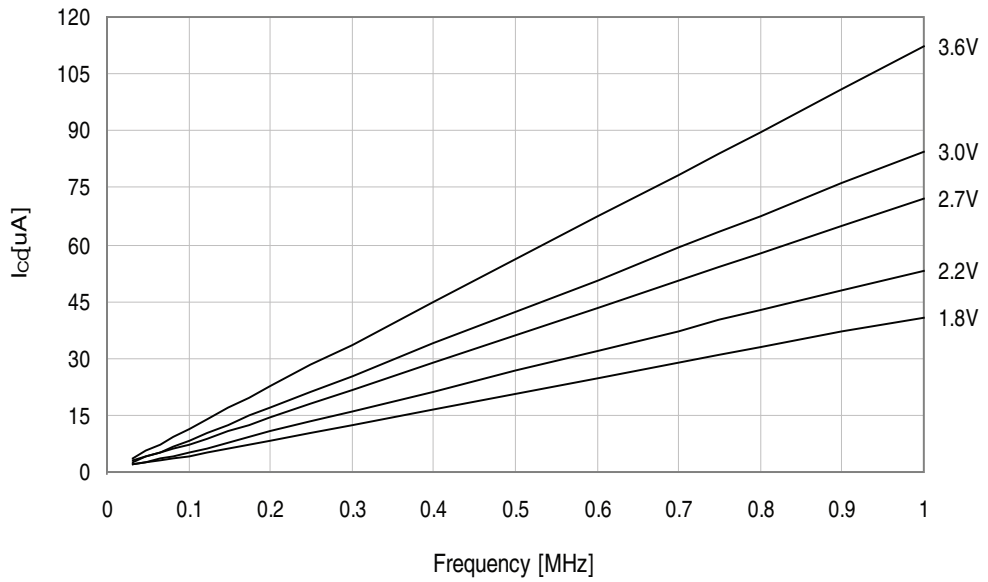


Figure 33-112. I/O Pin Input Threshold Voltage vs. V_{CC}

V_{IH} I/O pin read as "1"

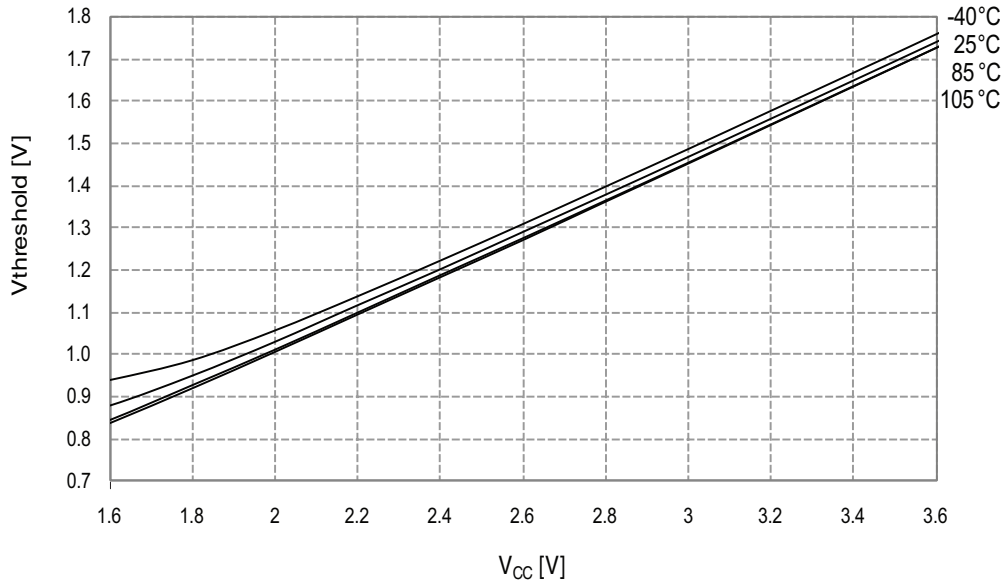


Figure 33-113. I/O Pin Input Threshold Voltage vs. V_{CC}

V_{IL} I/O pin read as "0"

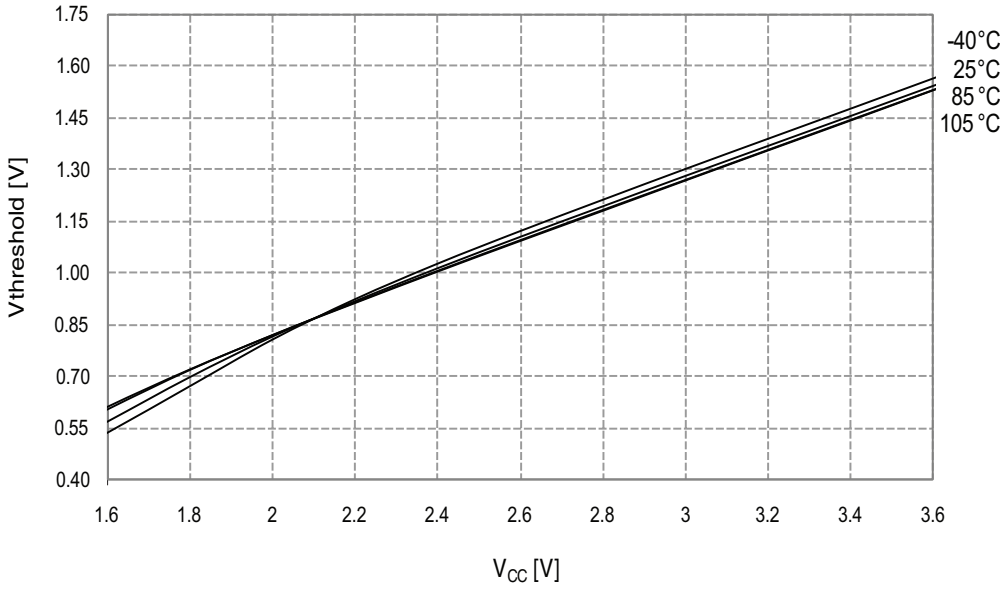


Figure 33-267. I/O Pin Output Voltage vs. Source Current

V_{CC} = 3.0V

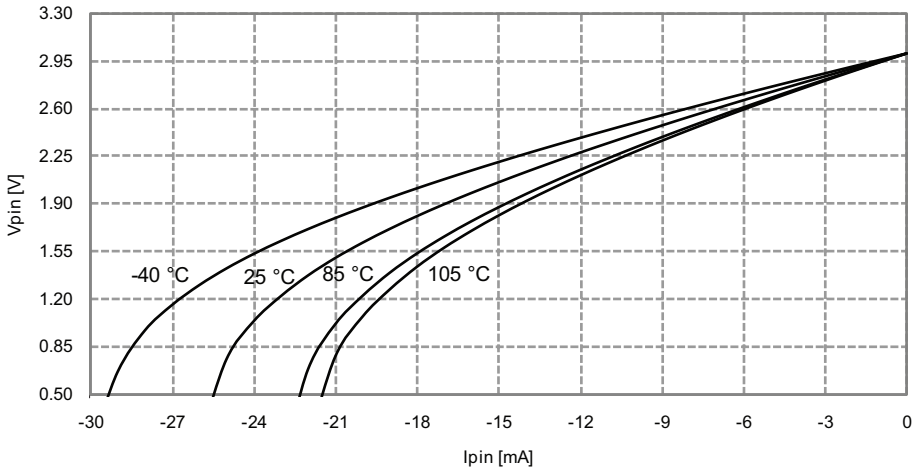


Figure 33-268. I/O Pin Output Voltage vs. Source Current

V_{CC} = 3.3V

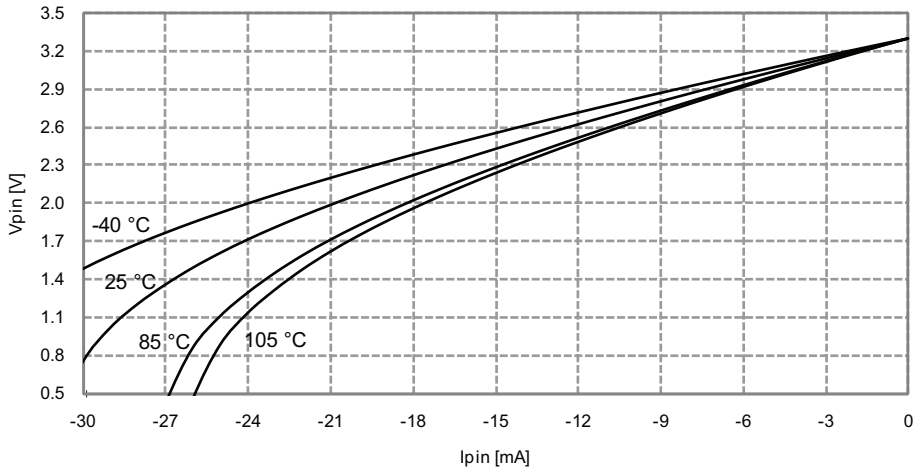
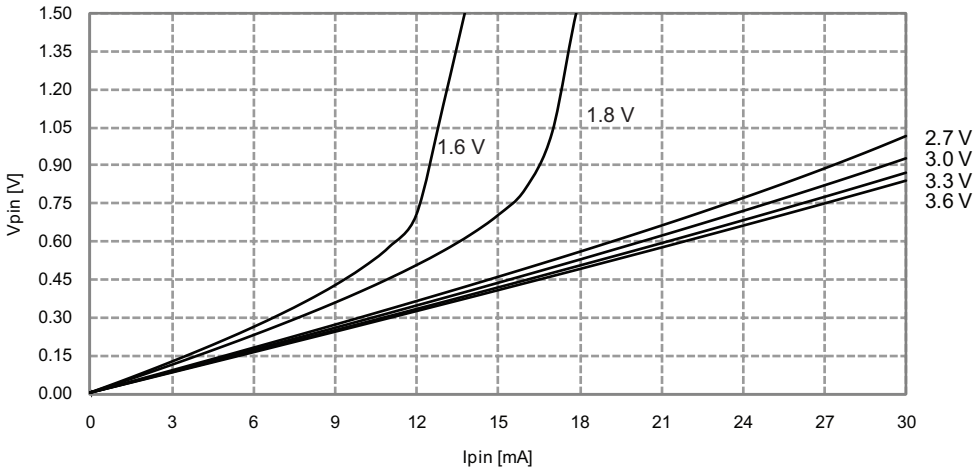


Figure 33-273. I/O Pin Output Voltage vs. Sink Current



33.4.2.3 Thresholds and Hysteresis

Figure 33-274. I/O Pin Input Threshold Voltage vs. V_{CC}

T = 25°C

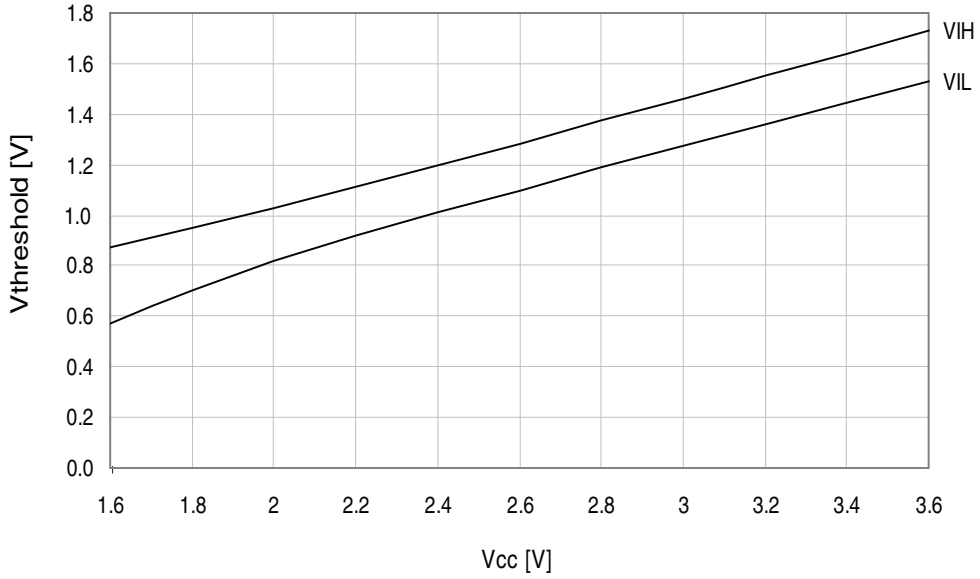


Figure 33-283. DNL Error vs. Input Code

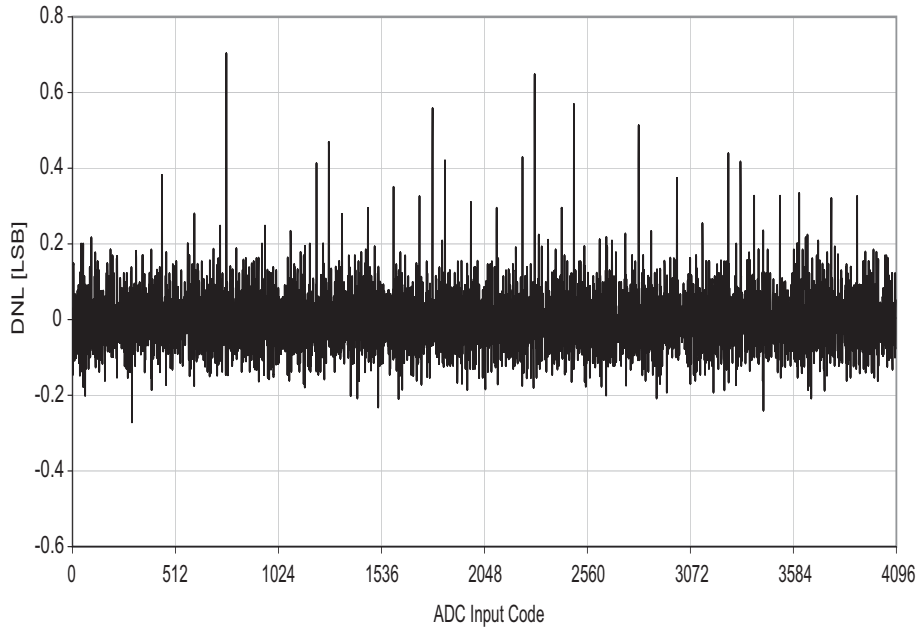


Figure 33-284. Gain Error vs. V_{REF}

T = 25°C, V_{CC} = 3.6V, ADC sampling speed = 500ksps

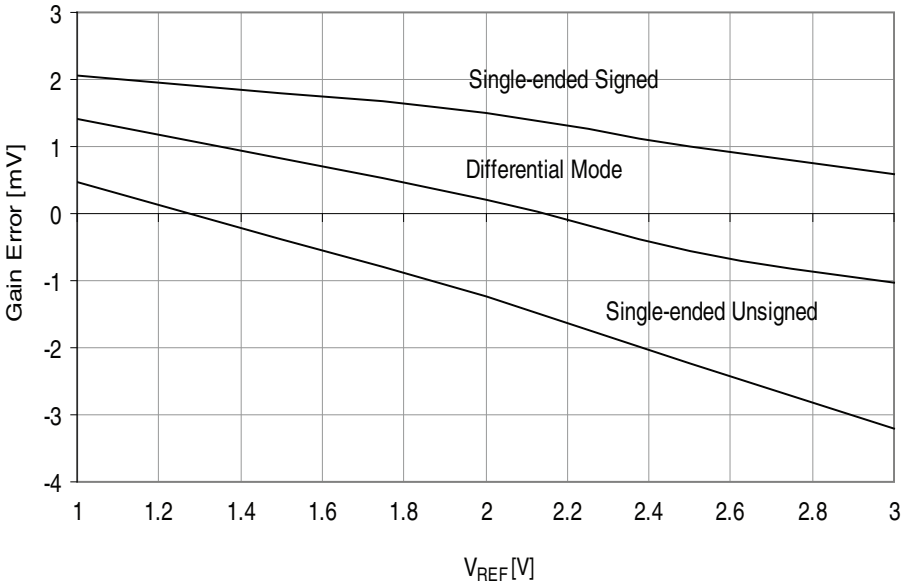
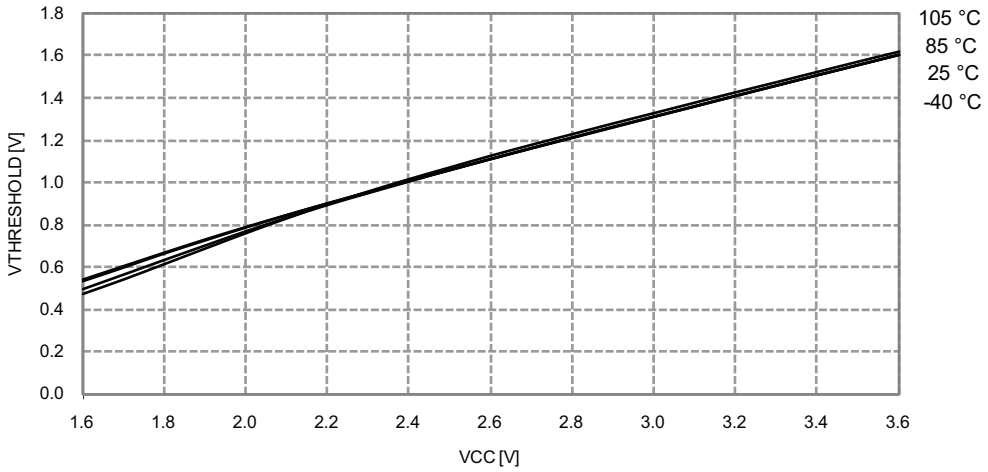


Figure 33-309. Reset Pin Input Threshold Voltage vs. V_{CC}

V_{IL} - Reset pin read as "0"



33.4.9 Power-on Reset Characteristics

Figure 33-310. Power-on Reset Current Consumption vs. V_{CC}

BOD level = 3.0V, enabled in continuous mode

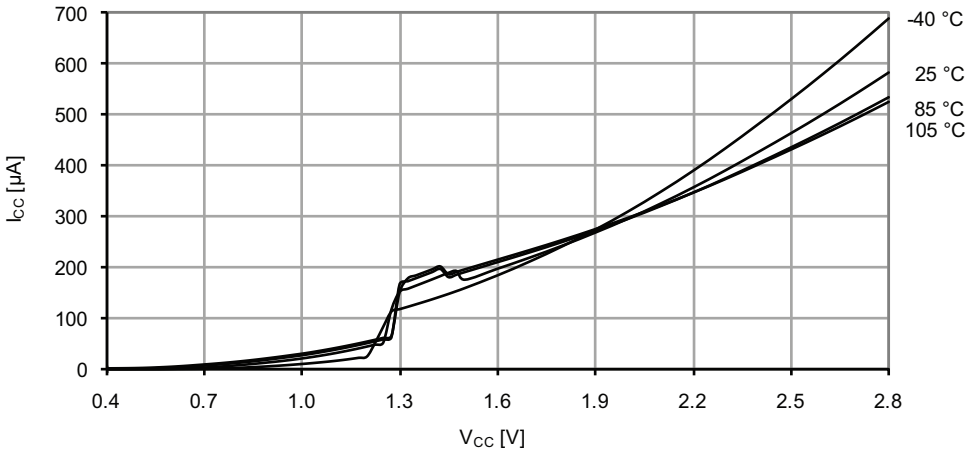
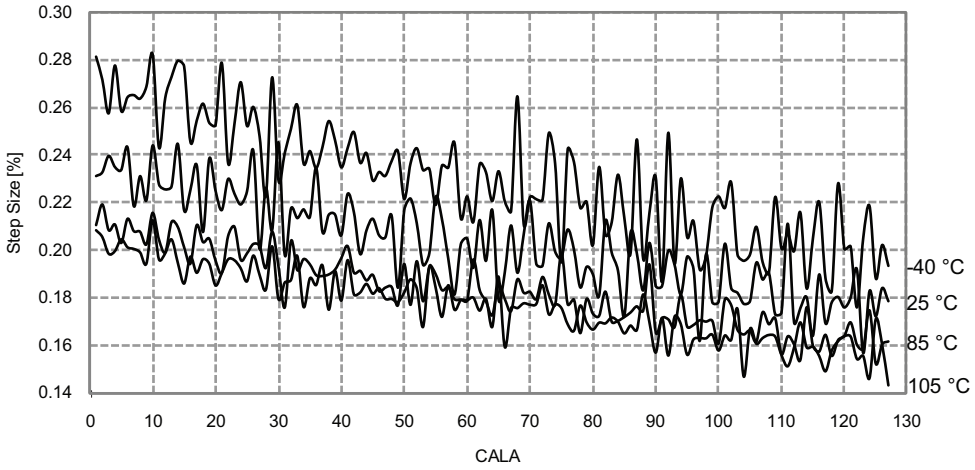


Figure 33-317. 2MHz Internal Oscillator CALA Calibration Step Size

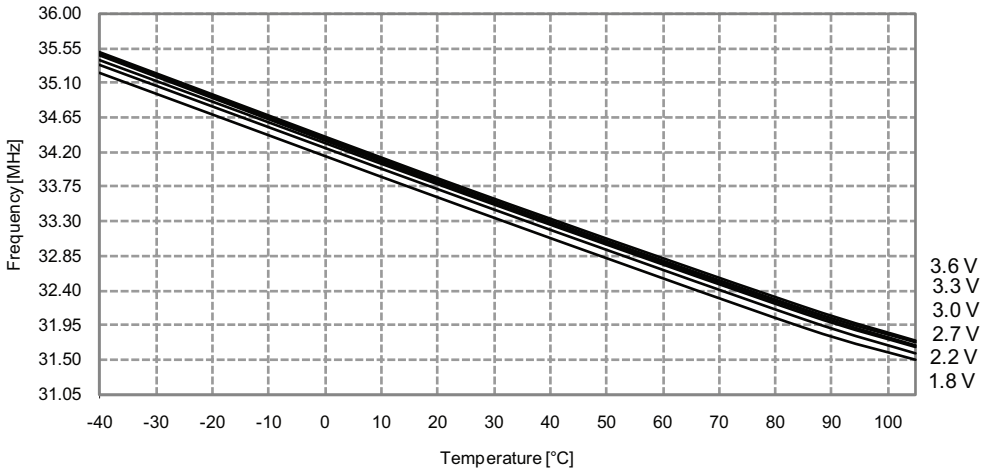
V_{CC} = 3V



33.4.10.4 32MHz Internal Oscillator

Figure 33-318. 32MHz Internal Oscillator Frequency vs. Temperature

DFLL disabled



Problem fix/Workaround

For CWCM no workaround is required.

For PGM in latched mode, disable the DTI channels before returning from the fault condition. Then, set correct OUTOVEN value and enable the DTI channels, before the direction (DIR) register is written to enable the correct outputs again.

For PGM in cycle-by-cycle mode there is no workaround.

4. **Erroneous interrupt when using Timer/Counter with QDEC**

   When the Timer/Counter is set in Dual Slope mode with QDEC enabled, an additional underflow interrupt (and event) will be given when the counter counts from BOTTOM to one.

   Problem fix/Workaround

   When receiving underflow interrupt check direction and value of counter. If direction is UP and counter value is zero, change the counter value to one. This will also remove the additional event. If the counter value is above zero, clear the interrupt flag.

5. **AC system status flags are only valid if AC-system is enabled**

   The status flags for the ac-output are updated even though the AC is not enabled which is invalid. Also, it is not possible to clear the AC interrupt flags without enabling either of the Analog comparators.

   Problem fix/Workaround

   Software should clear the AC system flags once, after enabling the AC system before using the AC system status flags.

6. **Temperature sensor not calibrated**

   Temperature sensor factory calibration not implemented.

   Problem fix/Workaround

   None.

34.1.4 Rev. C/D

Not sampled.